

**SN54LVTH573, SN74LVTH573**  
**3.3-V ABT OCTAL TRANSPARENT D-TYPE LATCHES**  
**WITH 3-STATE OUTPUTS**

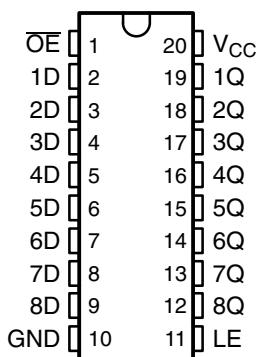
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- Support Mixed-Mode Signal Operation (5-V Input and Output Voltages With 3.3-V  $V_{CC}$ )
- Support Unregulated Battery Operation Down to 2.7 V
- Typical  $V_{OLP}$  (Output Ground Bounce) <0.8 V at  $V_{CC} = 3.3$  V,  $T_A = 25^\circ\text{C}$
- $I_{off}$  and Power-Up 3-State Support Hot Insertion
- Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors
- Latch-Up Performance Exceeds 500 mA Per JESD 17
- ESD Protection Exceeds JESD 22
  - 2000-V Human-Body Model (A114-A)
  - 200-V Machine Model (A115-A)

**SN54LVTH573 . . . J OR W PACKAGE**

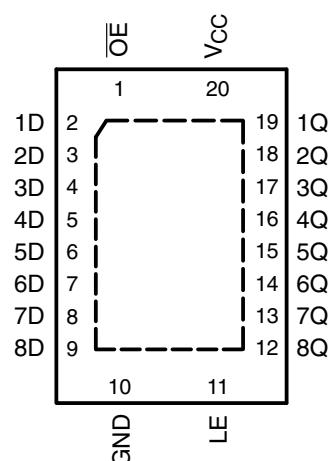
**SN74LVTH573 . . . DB, DW, NS,**

**OR PW PACKAGE  
(TOP VIEW)**



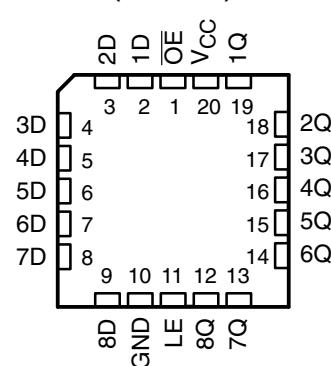
**SN74LVTH573 . . . RGY PACKAGE**

**(TOP VIEW)**



**SN54LVTH573 . . . FK PACKAGE**

**(TOP VIEW)**



### description/ordering information

#### ORDERING INFORMATION

<b><math>T_A</math></b>	<b>PACKAGE<sup>†</sup></b>		<b>ORDERABLE PART NUMBER</b>	<b>TOP-SIDE MARKING</b>
$-40^\circ\text{C}$ to $85^\circ\text{C}$	QFN – RGY	Tape and reel	SN74LVTH573RGYR	LXH573
	SOIC – DW	Tube	SN74LVTH573DW	LVTH573
		Tape and reel	SN74LVTH573DWR	LVTH573
	SOP – NS	Tape and reel	SN74LVTH573NSR	LVTH573
	SSOP – DB	Tape and reel	SN74LVTH573DBR	LXH573
	TSSOP – PW	Tube	SN74LVTH573PW	LXH573
		Tape and reel	SN74LVTH573PWR	
	VFBGA – GQN	Tape and reel	SN74LVTH573GQNR	LXH573
	VFBGA – ZQN (Pb-free)		SN74LVTH573ZQNR	
$-55^\circ\text{C}$ to $125^\circ\text{C}$	CDIP – J	Tube	SNJ54LVTH573J	SNJ54LVTH573J
	CFP – W	Tube	SNJ54LVTH573W	SNJ54LVTH573W
	LCCC – FK	Tube	SNJ54LVTH573FK	SNJ54LVTH573FK

<sup>†</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at [www.ti.com/sc/package](http://www.ti.com/sc/package).



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

**PRODUCTION DATA** information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



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 On products compliant to MIL-PRF-38535, all parameters are tested unless otherwise noted. On all other products, production processing does not necessarily include testing of all parameters.

# SN54LVTH573, SN74LVTH573

## 3.3-V ABT OCTAL TRANSPARENT D-TYPE LATCHES WITH 3-STATE OUTPUTS

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### description/ordering information (continued)

These octal latches are designed specifically for low-voltage (3.3-V)  $V_{CC}$  operation, but with the capability to provide a TTL interface to a 5-V system environment.

The eight latches of the 'LVTH573 devices are transparent D-type latches. While the latch-enable (LE) input is high, the Q outputs follow the data (D) inputs. When LE is taken low, the Q outputs are latched at the logic levels set up at the D inputs.

A buffered output-enable ( $\overline{OE}$ ) input can be used to place the eight outputs in either a normal logic state (high or low logic levels) or a high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines without need for interface or pullup components.

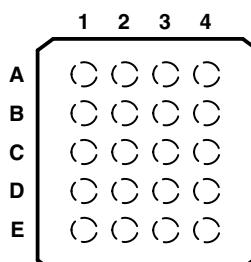
$\overline{OE}$  does not affect the internal operations of the latches. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

To ensure the high-impedance state during power up or power down,  $\overline{OE}$  should be tied to  $V_{CC}$  through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level. Use of pullup or pulldown resistors with the bus-hold circuitry is not recommended.

These devices are fully specified for hot-insertion applications using  $I_{off}$  and power-up 3-state. The  $I_{off}$  circuitry disables the outputs, preventing damaging current backflow through the devices when they are powered down. The power-up 3-state circuitry places the outputs in the high-impedance state during power up and power down, which prevents driver conflict.

SN74LVTH573 . . . GQN OR ZQN PACKAGE  
(TOP VIEW)



terminal assignments

	1	2	3	4
A	1D	$\overline{OE}$	$V_{CC}$	1Q
B	3D	3Q	2D	2Q
C	5D	4D	5Q	4Q
D	7D	7Q	6D	6Q
E	GND	8D	LE	8Q

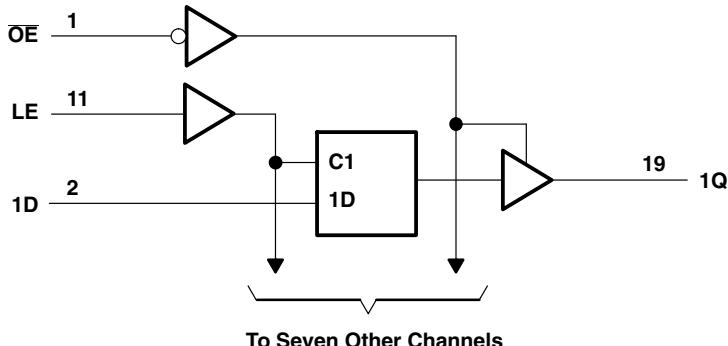
FUNCTION TABLE  
(each latch)

INPUTS			OUTPUT Q
$\overline{OE}$	LE	D	
L	H	H	H
L	H	L	L
L	L	X	$Q_0$
H	X	X	Z



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## logic diagram (positive logic)



Pin numbers shown are for the DB, DW, FK, J, NS, PW, RGY, and W packages.

**absolute maximum ratings over operating free-air temperature range (unless otherwise noted)<sup>†</sup>**

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

2. This current flows only when the output is in the high state and  $V_O > V_{CC}$ .
3. The package thermal impedance is calculated in accordance with JESD 51-7.
4. The package thermal impedance is calculated in accordance with JESD 51-5.

# SN54LVTH573, SN74LVTH573

## 3.3-V ABT OCTAL TRANSPARENT D-TYPE LATCHES WITH 3-STATE OUTPUTS

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### recommended operating conditions (see Note 5)

		SN54LVTH573		SN74LVTH573		UNIT
		MIN	MAX	MIN	MAX	
V <sub>CC</sub>	Supply voltage	2.7	3.6	2.7	3.6	V
V <sub>IH</sub>	High-level input voltage	2		2		V
V <sub>IL</sub>	Low-level input voltage			0.8	0.8	V
V <sub>I</sub>	Input voltage			5.5	5.5	V
I <sub>OH</sub>	High-level output current			-24	-32	mA
I <sub>OL</sub>	Low-level output current			48	64	mA
Δt/Δv	Input transition rise or fall rate	Outputs enabled		10	10	ns/V
Δt/ΔV <sub>CC</sub>	Power-up ramp rate			200	200	μs/V
T <sub>A</sub>	Operating free-air temperature	-55	125	-40	85	°C

NOTE 5: All unused control inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.



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**3.3-V ABT OCTAL TRANSPARENT D-TYPE LATCHES**  
**WITH 3-STATE OUTPUTS**

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**electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)**

PARAMETER	TEST CONDITIONS	SN54LVTH573			SN74LVTH573			UNIT
		MIN	TYP†	MAX	MIN	TYP†	MAX	
$V_{IK}$	$V_{CC} = 2.7 \text{ V}$ , $I_I = -18 \text{ mA}$			-1.2			-1.2	V
$V_{OH}$	$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$ , $I_{OH} = -100 \mu\text{A}$	$V_{CC} - 0.2$			$V_{CC} - 0.2$			V
	$V_{CC} = 2.7 \text{ V}$ , $I_{OH} = -8 \text{ mA}$	2.4			2.4			
	$V_{CC} = 3 \text{ V}$	$I_{OH} = -24 \text{ mA}$	2					
		$I_{OH} = -32 \text{ mA}$				2		
$V_{OL}$	$V_{CC} = 2.7 \text{ V}$	$I_{OL} = 100 \mu\text{A}$		0.2		0.2		V
		$I_{OL} = 24 \text{ mA}$		0.5		0.5		
	$V_{CC} = 3 \text{ V}$	$I_{OL} = 16 \text{ mA}$		0.4		0.4		
		$I_{OL} = 32 \text{ mA}$		0.5		0.5		
		$I_{OL} = 48 \text{ mA}$		0.55				
		$I_{OL} = 64 \text{ mA}$					0.55	
$I_I$	Control inputs	$V_{CC} = 0 \text{ or } 3.6 \text{ V}$ , $V_I = 5.5 \text{ V}$		10		10		$\mu\text{A}$
		$V_{CC} = 3.6 \text{ V}$ , $V_I = V_{CC} \text{ or GND}$		$\pm 1$		$\pm 1$		
	Data inputs	$V_{CC} = 3.6 \text{ V}$	$V_I = V_{CC}$	1		1		
			$V_I = 0$	-5		-5		
$I_{off}$		$V_{CC} = 0$ , $V_I \text{ or } V_O = 0 \text{ to } 4.5 \text{ V}$					$\pm 100$	$\mu\text{A}$
$I_{I(hold)}$	Data inputs	$V_{CC} = 3 \text{ V}$	$V_I = 0.8 \text{ V}$	75		75		$\mu\text{A}$
			$V_I = 2 \text{ V}$	-75		-75		
		$V_{CC} = 3.6 \text{ V}^\ddagger$	$V_I = 0 \text{ to } 3.6 \text{ V}$				$\pm 500$	
$I_{OZH}$		$V_{CC} = 3.6 \text{ V}$ , $V_O = 3 \text{ V}$		5		5	$\mu\text{A}$	
$I_{OZL}$		$V_{CC} = 3.6 \text{ V}$ , $V_O = 0.5 \text{ V}$		-5		-5	$\mu\text{A}$	
$I_{OZPU}$		$V_{CC} = 0 \text{ to } 1.5 \text{ V}$ , $V_O = 0.5 \text{ V to } 3 \text{ V}$ , $OE = \text{don't care}$		$\pm 100^*$		$\pm 100$	$\mu\text{A}$	
$I_{OZPD}$		$V_{CC} = 1.5 \text{ V to } 0$ , $V_O = 0.5 \text{ V to } 3 \text{ V}$ , $OE = \text{don't care}$		$\pm 100^*$		$\pm 100$	$\mu\text{A}$	
$I_{CC}$	$V_{CC} = 3.6 \text{ V}$ , $I_O = 0$ , $V_I = V_{CC} \text{ or GND}$	Outputs high		0.19		0.19		$\text{mA}$
		Outputs low		5		5		
		Outputs disabled		0.19		0.19		
$\Delta I_{CC}^\S$		$V_{CC} = 3 \text{ V to } 3.6 \text{ V}$ , One input at $V_{CC} - 0.6 \text{ V}$ , Other inputs at $V_{CC}$ or GND		0.2		0.2	$\text{mA}$	
$C_I$		$V_I = 3 \text{ V or } 0$		3		3	$\text{pF}$	
$C_O$		$V_O = 3 \text{ V or } 0$		7		7	$\text{pF}$	

\*On products compliant to MIL-PRF-38535, this parameter is not production tested.

† All typical values are at  $V_{CC} = 3.3 \text{ V}$ ,  $T_A = 25^\circ\text{C}$ .

‡ This is the bus-hold maximum dynamic current. It is the minimum overdrive current required to switch the input from one state to another.

§ This is the increase in supply current for each input that is at the specified TTL voltage level, rather than  $V_{CC}$  or GND.

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**timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)**

		SN54LVTH573				SN74LVTH573				UNIT	
		V <sub>CC</sub> = 3.3 V ± 0.3 V		V <sub>CC</sub> = 2.7 V		V <sub>CC</sub> = 3.3 V ± 0.3 V		V <sub>CC</sub> = 2.7 V			
		MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX		
t <sub>w</sub>	Pulse duration, LE high	3		3		3		3		ns	
t <sub>su</sub>	Setup time, data before LE↓	0.7		0.6		0.7		0.6		ns	
t <sub>h</sub>	Hold time, data after LE↓	1.5		1.7		1.5		1.7		ns	

**switching characteristics over recommended free-air temperature, C<sub>L</sub> = 50 pF (unless otherwise noted) (see Figure 1)**

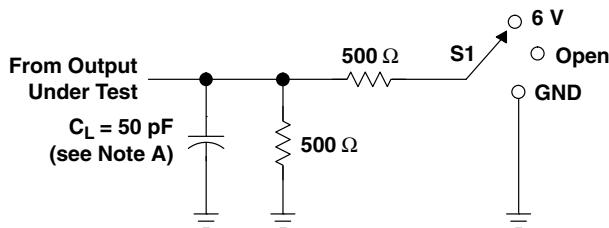
PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN54LVTH573				SN74LVTH573				UNIT	
			V <sub>CC</sub> = 3.3 V ± 0.3 V		V <sub>CC</sub> = 2.7 V		V <sub>CC</sub> = 3.3 V ± 0.3 V		V <sub>CC</sub> = 2.7 V			
			MIN	MAX	MIN	MAX	MIN	TYP <sup>†</sup>	MAX	MIN		
t <sub>PLH</sub>	D	Q	1.4	4.1		4.7	1.5	2.6	3.9	4.5	ns	
t <sub>PHL</sub>			1.4	4.5		4.8	1.5	2.9	3.9	4.5		
t <sub>PLH</sub>	LE	Q	1	4.4		5.4	1.9	2.9	4.2	4.9	ns	
t <sub>PHL</sub>			1.4	4.4		5.1	1.9	2.9	4.2	4.9		
t <sub>PZH</sub>	OE	Q	1.4	5.2		6.2	1.5	3.2	5.1	5.9	ns	
t <sub>PZL</sub>			1.4	5.2		6.2	1.5	3.9	5.1	5.9		
t <sub>PHZ</sub>	OE	Q	1.2	5.4		5.7	2	3.5	4.9	5.5	ns	
t <sub>PLZ</sub>			1	5.2		5.2	2	3.2	4.6	4.9		

<sup>†</sup> All typical values are at V<sub>CC</sub> = 3.3 V, T<sub>A</sub> = 25°C.

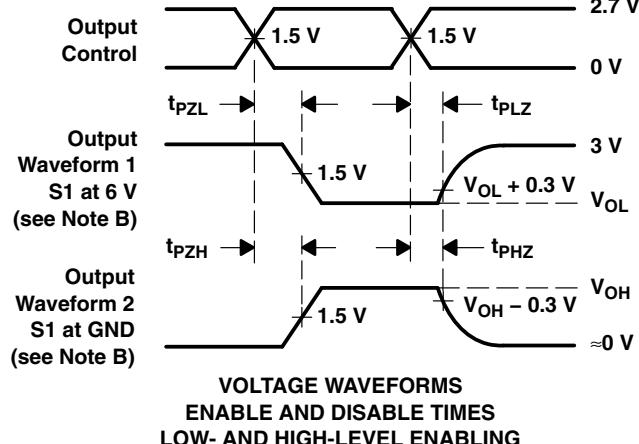
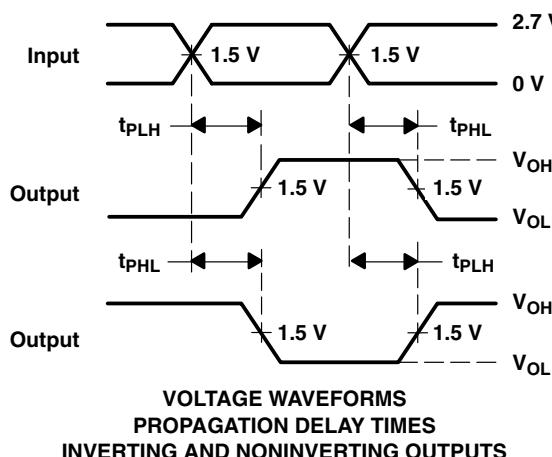
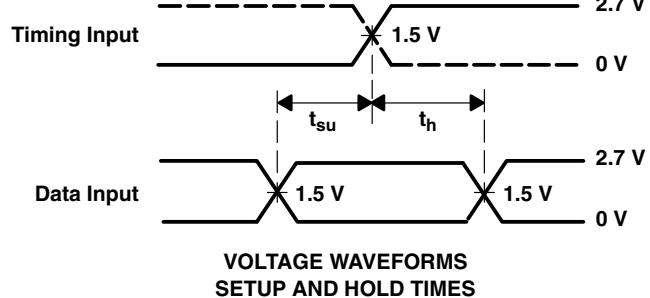
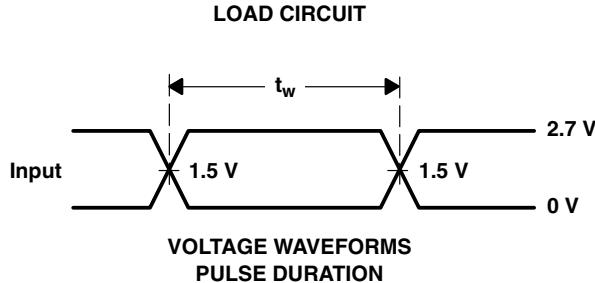


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**PARAMETER MEASUREMENT INFORMATION**



TEST	S1
$t_{PLH}/t_{PHL}$	Open
$t_{PLZ}/t_{PZL}$	6 V
$t_{PHZ}/t_{PZH}$	GND



NOTES:

- $C_L$  includes probe and jig capacitance.
- Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- All input pulses are supplied by generators having the following characteristics: PRR  $\leq 10 \text{ MHz}$ ,  $Z_O = 50 \Omega$ ,  $t_r \leq 2.5 \text{ ns}$ ,  $t_f \leq 2.5 \text{ ns}$ .
- The outputs are measured one at a time with one transition per measurement.
- All parameters and waveforms are not applicable to all devices.

**Figure 1. Load Circuit and Voltage Waveforms**

## PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
5962-9583101Q2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	5962-9583101Q2A SNJ54LVTH573FK	Samples
5962-9583101QRA	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9583101QR A SNJ54LVTH573J	Samples
5962-9583101QSA	ACTIVE	CFP	W	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9583101QS A SNJ54LVTH573W	Samples
SN74LVTH573DBLE	OBsolete	SSOP	DB	20		TBD	Call TI	Call TI	-40 to 85		
SN74LVTH573DBR	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LXH573	Samples
SN74LVTH573DBRE4	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LXH573	Samples
SN74LVTH573DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVTH573	Samples
SN74LVTH573DWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVTH573	Samples
SN74LVTH573DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVTH573	Samples
SN74LVTH573DWRE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVTH573	Samples
SN74LVTH573NSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVTH573	Samples
SN74LVTH573PW	ACTIVE	TSSOP	PW	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LXH573	Samples
SN74LVTH573PWG4	ACTIVE	TSSOP	PW	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LXH573	Samples
SN74LVTH573PWLE	OBsolete	TSSOP	PW	20		TBD	Call TI	Call TI	-40 to 85		
SN74LVTH573PWR	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LXH573	Samples
SN74LVTH573RGYR	ACTIVE	VQFN	RGY	20	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	LXH573	Samples

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SNJ54LVTH573FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	5962-9583101Q2A SNJ54LVTH573FK	<span style="background-color: red; color: white; padding: 2px;">Samples</span>
SNJ54LVTH573J	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9583101QR A SNJ54LVTH573J	<span style="background-color: red; color: white; padding: 2px;">Samples</span>
SNJ54LVTH573W	ACTIVE	CFP	W	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9583101QS A SNJ54LVTH573W	<span style="background-color: red; color: white; padding: 2px;">Samples</span>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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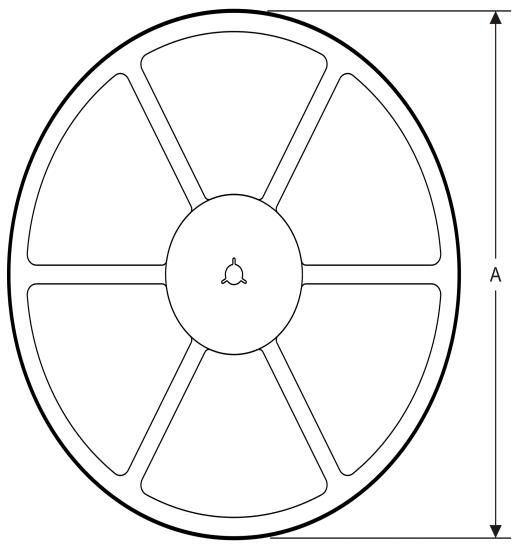
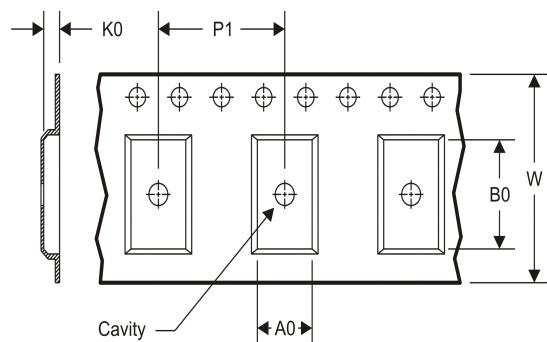
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**OTHER QUALIFIED VERSIONS OF SN54LVTH573, SN74LVTH573 :**

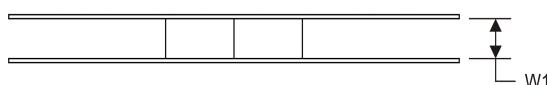
- Catalog: [SN74LVTH573](#)
- Enhanced Product: [SN74LVTH573-EP](#), [SN74LVTH573-EP](#)
- Military: [SN54LVTH573](#)

**NOTE: Qualified Version Definitions:**

- Catalog - TI's standard catalog product
- Enhanced Product - Supports Defense, Aerospace and Medical Applications
- Military - QML certified for Military and Defense Applications

**TAPE AND REEL INFORMATION**
**REEL DIMENSIONS**

**TAPE DIMENSIONS**


A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers


**TAPE AND REEL INFORMATION**

\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LVTH573DBR	SSOP	DB	20	2000	330.0	16.4	8.2	7.5	2.5	12.0	16.0	Q1
SN74LVTH573DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.0	2.7	12.0	24.0	Q1
SN74LVTH573NSR	SO	NS	20	2000	330.0	24.4	8.2	13.0	2.5	12.0	24.0	Q1
SN74LVTH573PWR	TSSOP	PW	20	2000	330.0	16.4	6.95	7.1	1.6	8.0	16.0	Q1
SN74LVTH573RGYR	VQFN	RGY	20	3000	330.0	12.4	3.8	4.8	1.6	8.0	12.0	Q1

**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LVTH573DBR	SSOP	DB	20	2000	367.0	367.0	38.0
SN74LVTH573DWR	SOIC	DW	20	2000	367.0	367.0	45.0
SN74LVTH573NSR	SO	NS	20	2000	367.0	367.0	45.0
SN74LVTH573PWR	TSSOP	PW	20	2000	367.0	367.0	38.0
SN74LVTH573RGYR	VQFN	RGY	20	3000	367.0	367.0	35.0

J (R-GDIP-T\*\*)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



PINS ** DIM	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)

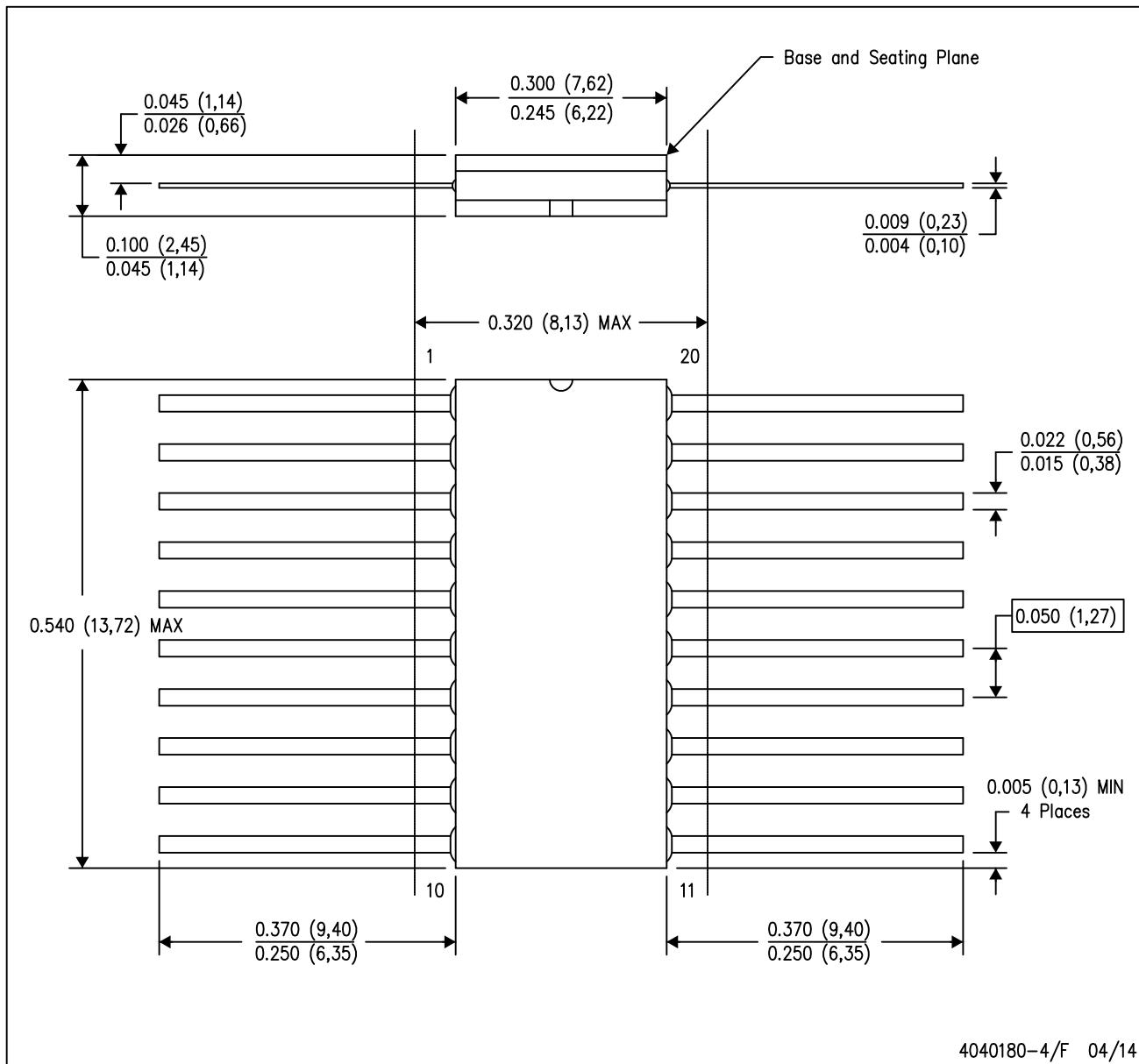


4040083/F 03/03

NOTES: A. All linear dimensions are in inches (millimeters).  
B. This drawing is subject to change without notice.  
C. This package is hermetically sealed with a ceramic lid using glass frit.  
D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.  
E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F20)

CERAMIC DUAL FLATPACK



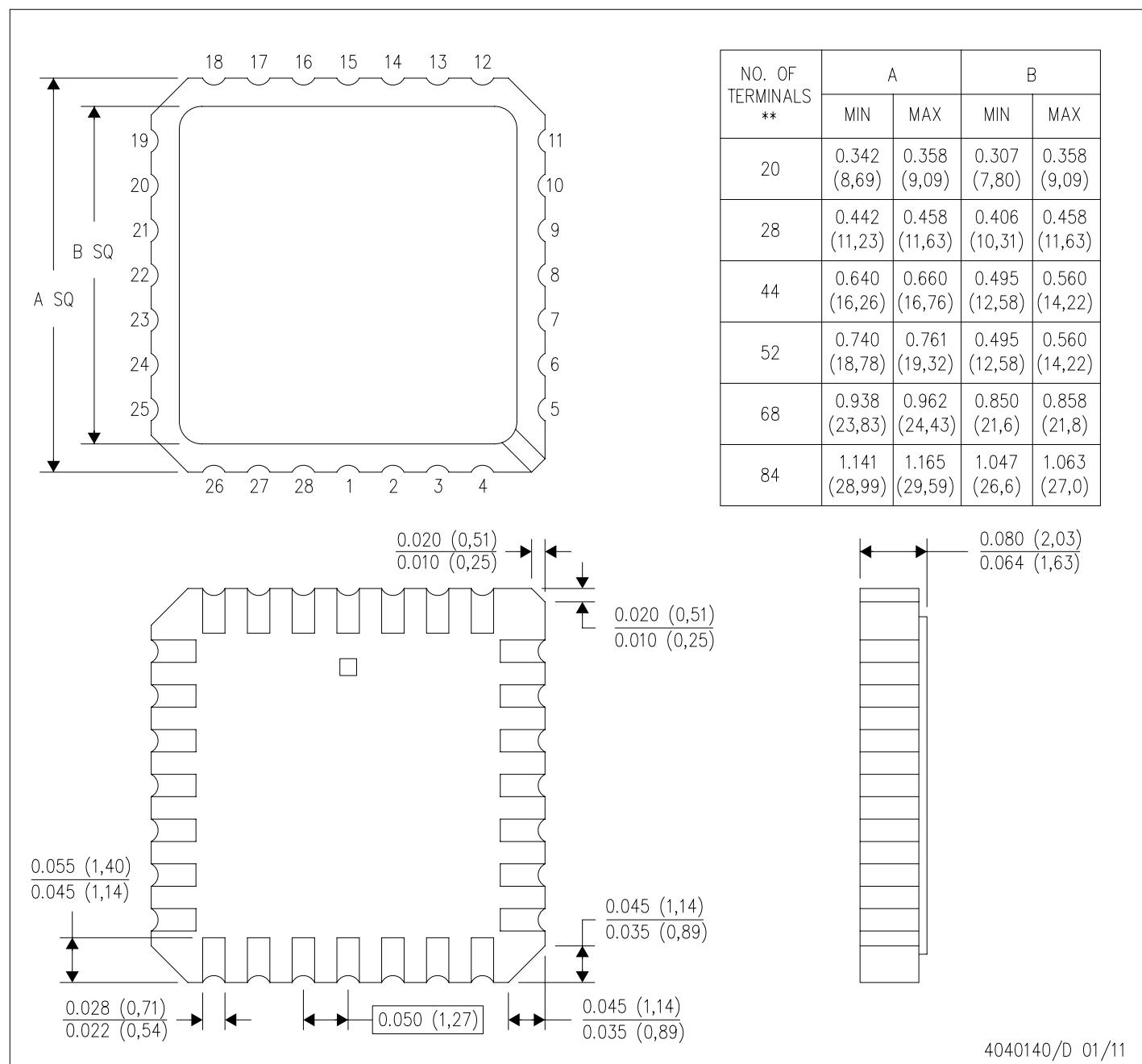
NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within Mil-Std 1835 GDFP2-F20

FK (S-CQCC-N\*\*)

28 TERMINAL SHOWN

LEADLESS CERAMIC CHIP CARRIER



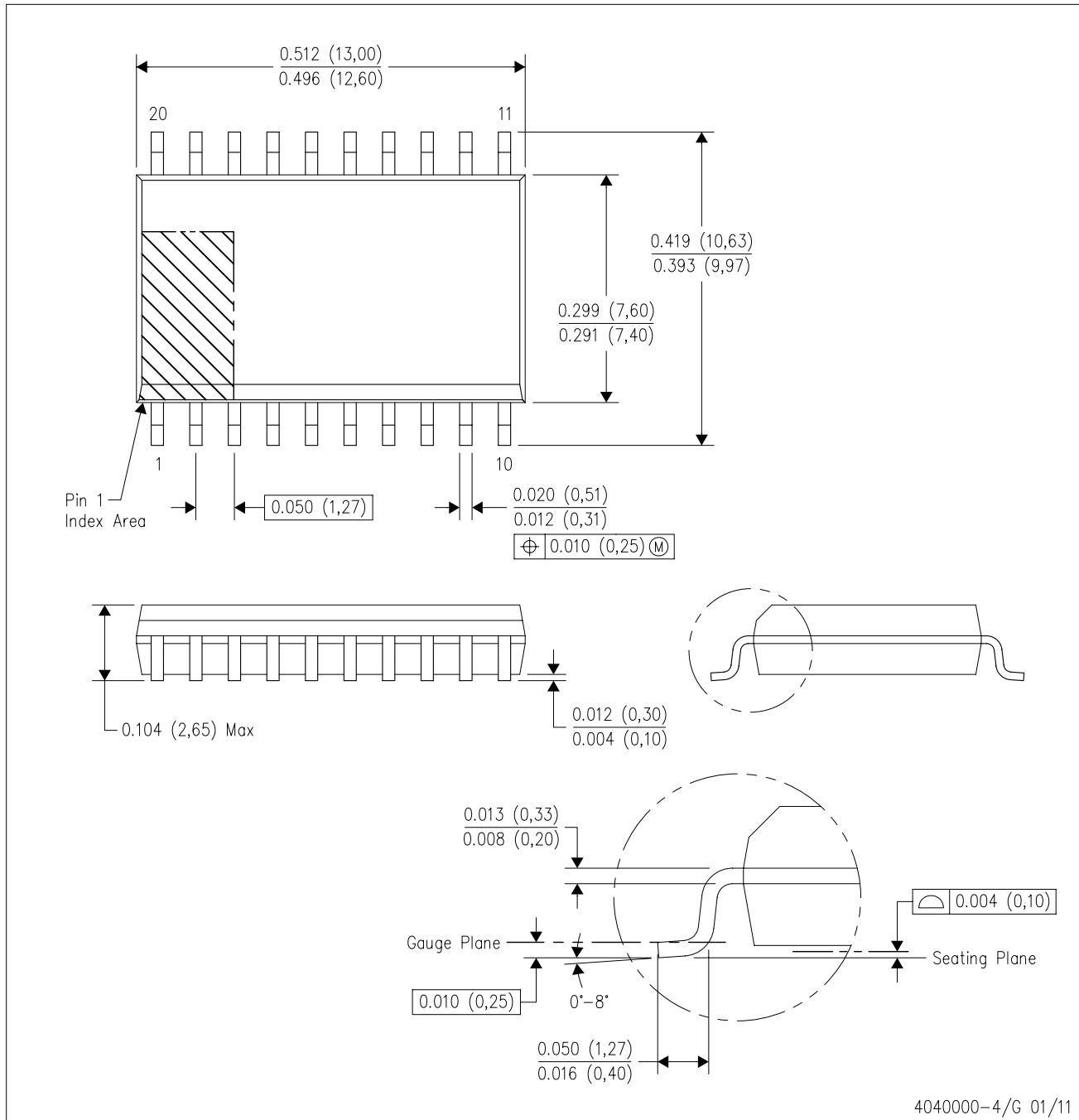
NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. Falls within JEDEC MS-004

4040140/D 01/11

DW (R-PDSO-G20)

PLASTIC SMALL OUTLINE

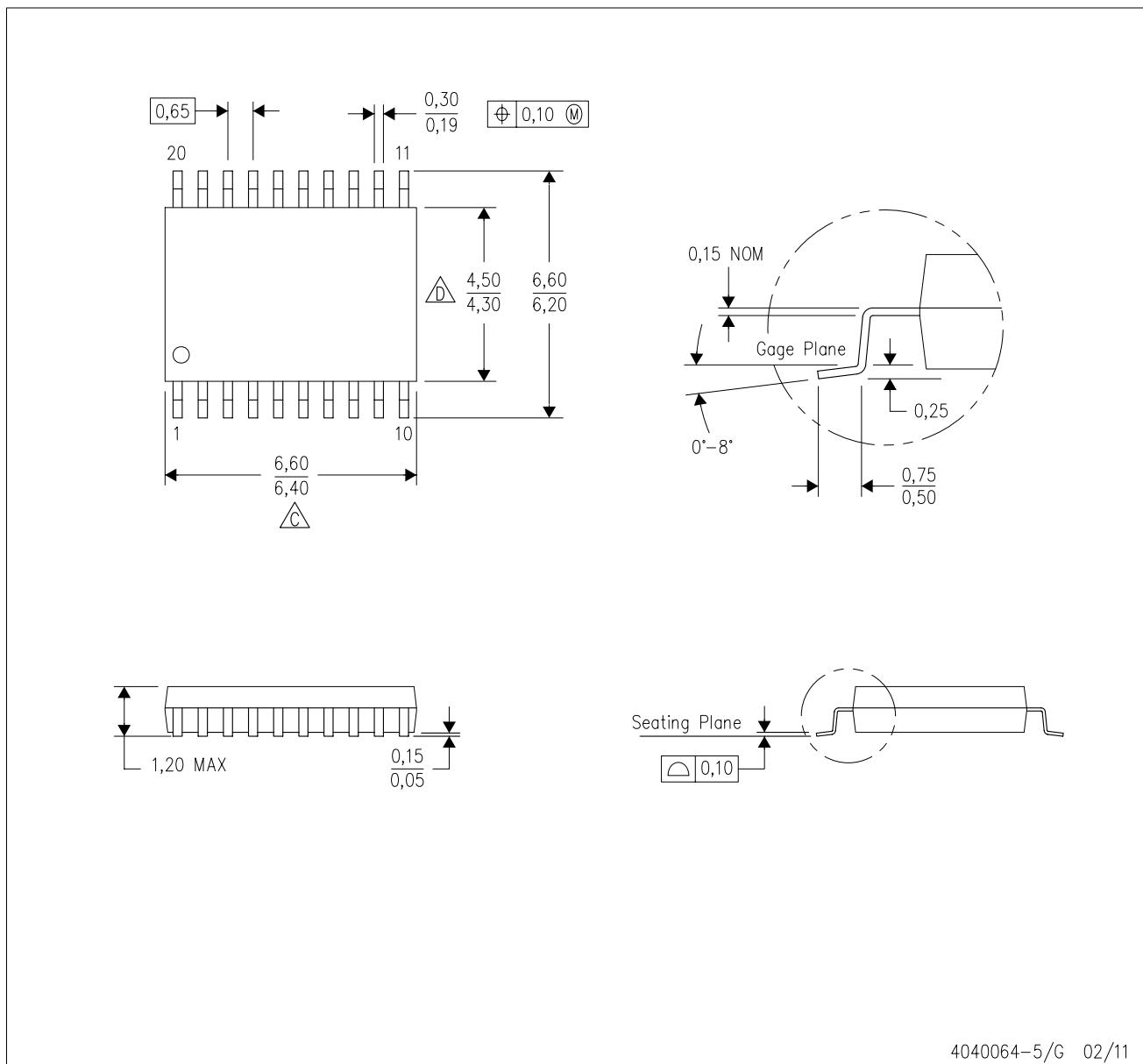


NOTES:

- All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.
- This drawing is subject to change without notice.
- Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0.15).
- Falls within JEDEC MS-013 variation AC.

PW (R-PDSO-G20)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.

B. This drawing is subject to change without notice.

 C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.

 D. Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.

E. Falls within JEDEC MO-153

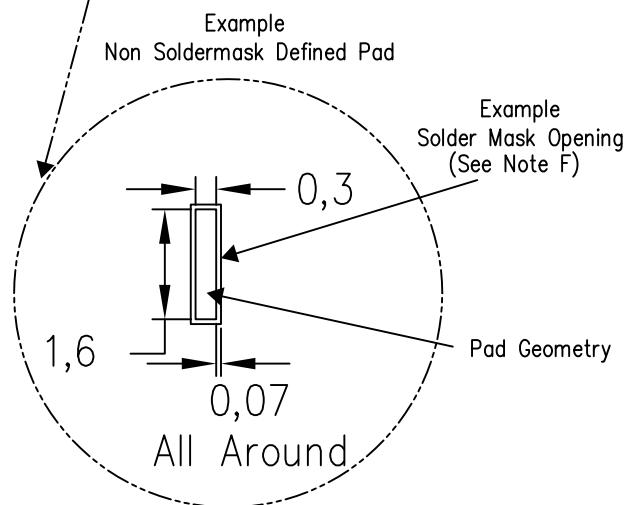
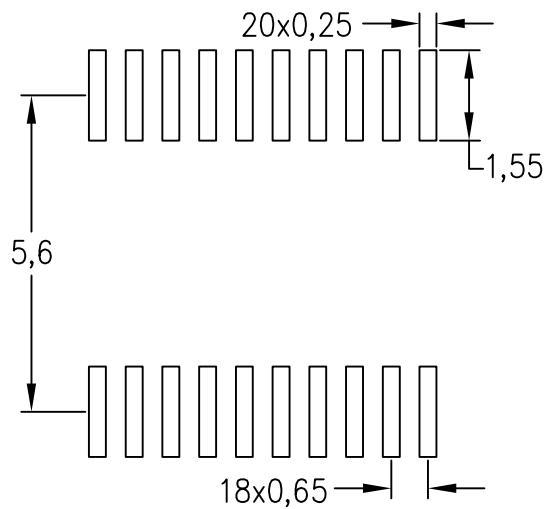
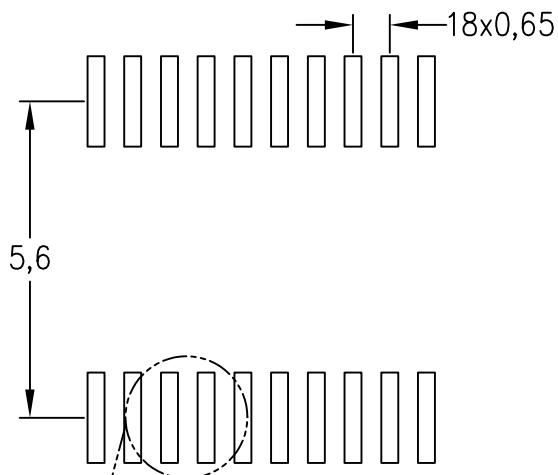
4040064-5/G 02/11

## PW (R-PDSO-G20)

## PLASTIC SMALL OUTLINE

## Example Board Layout

Based on a stencil thickness  
of .127mm (.005inch).



4211284-5/F 12/12

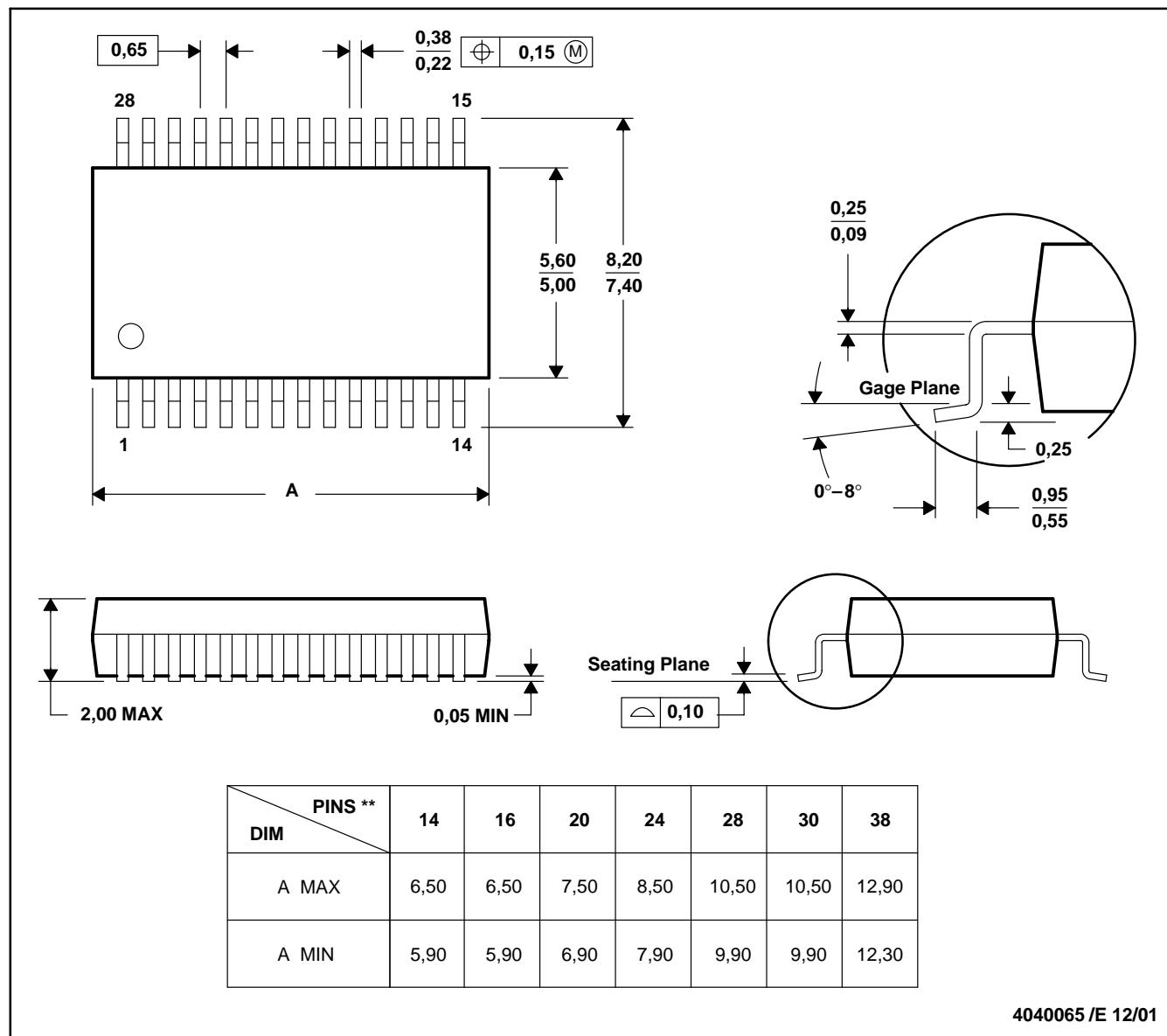
NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate design.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

## DB (R-PDSO-G\*\*)

## PLASTIC SMALL-OUTLINE

28 PINS SHOWN

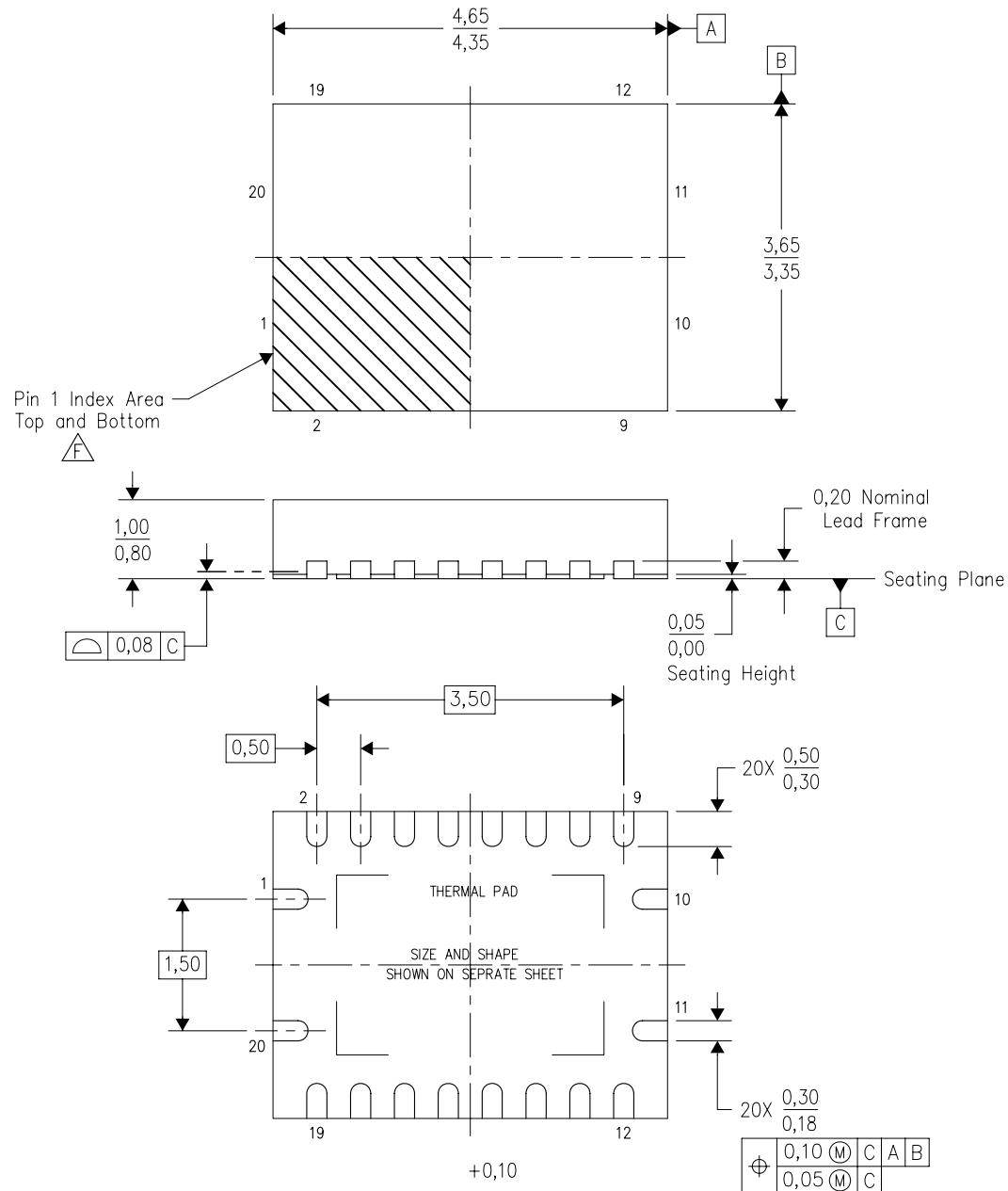


NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.  
 D. Falls within JEDEC MO-150

## MECHANICAL DATA

RGY (R-PVQFN-N20)

PLASTIC QUAD FLATPACK NO-LEAD



Bottom View

4203539-4/l 06/2011

NOTES:

- All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
- This drawing is subject to change without notice.
- QFN (Quad Flatpack No-Lead) package configuration.
- The package thermal pad must be soldered to the board for thermal and mechanical performance.
- See the additional figure in the Product Data Sheet for details regarding the exposed thermal pad features and dimensions.
- Pin 1 identifiers are located on both top and bottom of the package and within the zone indicated. The Pin 1 identifiers are either a molded, marked, or metal feature.
- Package complies to JEDEC MO-241 variation BA.

# THERMAL PAD MECHANICAL DATA

RGY (R-PVQFN-N20)

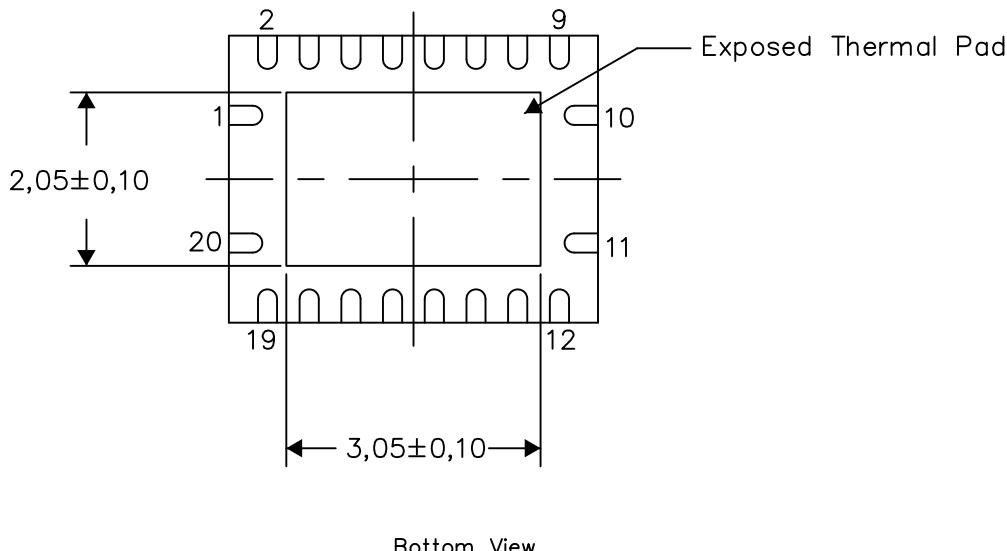
PLASTIC QUAD FLATPACK NO-LEAD

## THERMAL INFORMATION

This package incorporates an exposed thermal pad that is designed to be attached directly to an external heatsink. The thermal pad must be soldered directly to the printed circuit board (PCB). After soldering, the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to the appropriate copper plane shown in the electrical schematic for the device, or alternatively, can be attached to a special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

For information on the Quad Flatpack No-Lead (QFN) package and its advantages, refer to Application Report, QFN/SON PCB Attachment, Texas Instruments Literature No. SLUA271. This document is available at [www.ti.com](http://www.ti.com).

The exposed thermal pad dimensions for this package are shown in the following illustration.



Bottom View

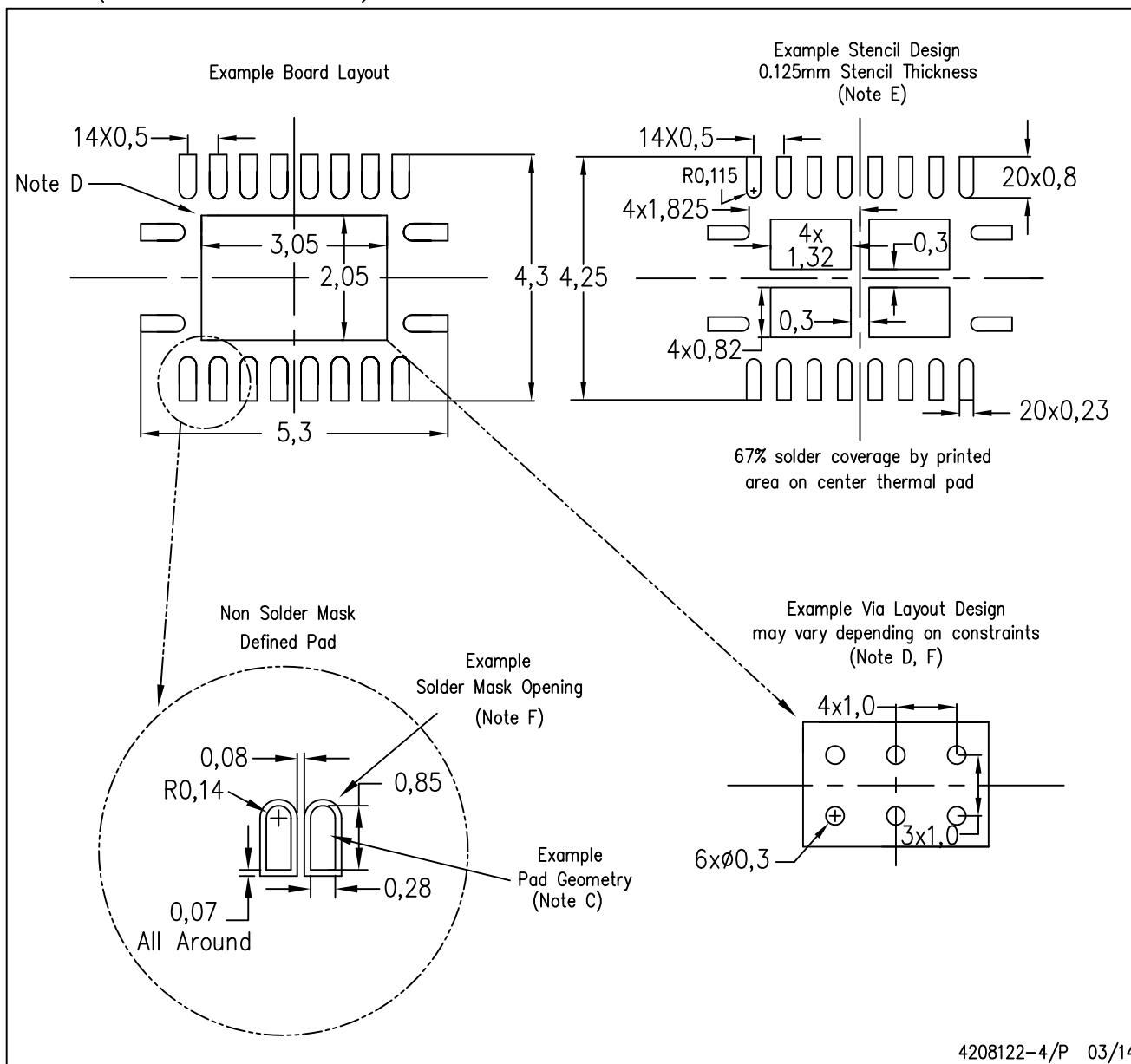
Exposed Thermal Pad Dimensions

4206353-4/P 03/14

NOTE: All linear dimensions are in millimeters

RGY (R-PVQFN-N20)

PLASTIC QUAD FLATPACK NO-LEAD



4208122-4/P 03/14

NOTES:

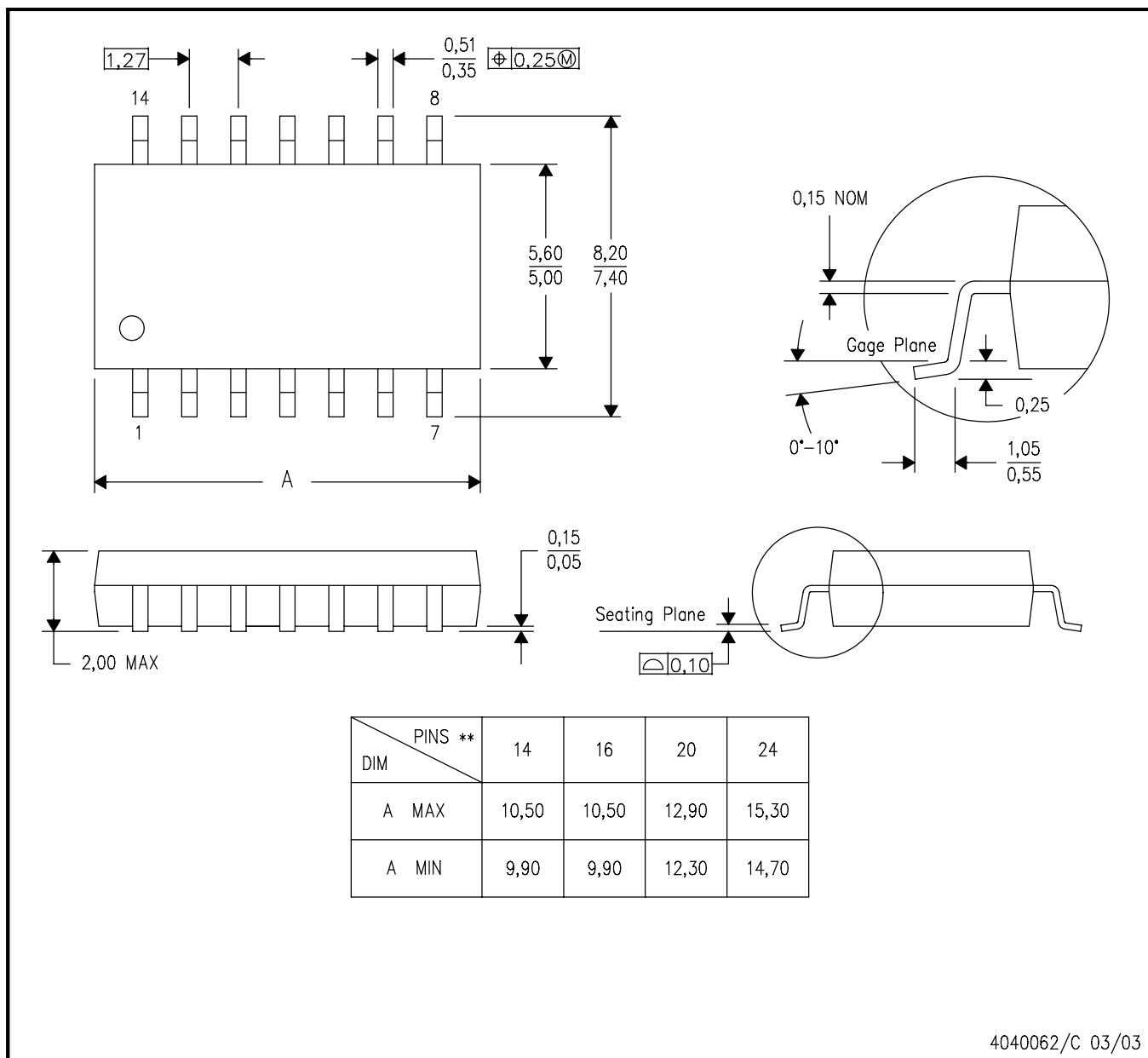
- All linear dimensions are in millimeters.
- This drawing is subject to change without notice.
- Publication IPC-7351 is recommended for alternate designs.
- This package is designed to be soldered to a thermal pad on the board. Refer to Application Note, Quad Flat-Pack QFN/SON PCB Attachment, Texas Instruments Literature No. SLUA271, and also the Product Data Sheets for specific thermal information, via requirements, and recommended board layout. These documents are available at [www.ti.com](http://www.ti.com) <<http://www.ti.com>>.
- Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC 7525 for stencil design considerations.
- Customers should contact their board fabrication site for minimum solder mask web tolerances between signal pads.

## MECHANICAL DATA

NS (R-PDSO-G\*\*)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

4040062/C 03/03

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DLP® Products	<a href="http://www.dlp.com">www.dlp.com</a>
DSP	<a href="http://dsp.ti.com">dsp.ti.com</a>
Clocks and Timers	<a href="http://www.ti.com/clocks">www.ti.com/clocks</a>
Interface	<a href="http://interface.ti.com">interface.ti.com</a>
Logic	<a href="http://logic.ti.com">logic.ti.com</a>
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Wireless Connectivity	<a href="http://www.ti.com/wirelessconnectivity">www.ti.com/wirelessconnectivity</a>
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